

# IRF530 IRF530FI

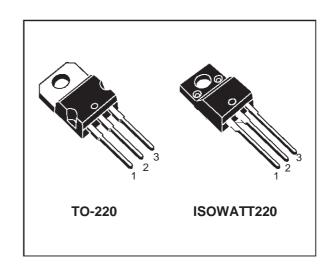
# N - CHANNEL ENHANCEMENT MODE POWER MOS TRANSISTOR

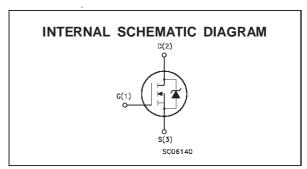
TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
IRF530	100 V	< 0.16 Ω	16 A
IRF530FI	100 V	< 0.16 Ω	11 A

- TYPICAL  $R_{DS(on)} = 0.12 \Omega$
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- REPETITIVE AVALANCHE DATA AT 100°C
- LOW GATE CHARGE
- HIGH CURRENT CAPABILITY
- 175°C OPERATING TEMPERATURE
- APPLICATION ORIENTED CHARACTERIZATION

#### **APPLICATIONS**

- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- DC-DC & DC-AC CONVERTER
- AUTOMOTIVE ENVIRONMENT (INJECTION, ABS, AIR-BAG, LAMP DRIVERS Etc.)





#### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Va	Value	
		IRF530	IRF530FI	
V <sub>DS</sub>	Drain-source Voltage (V <sub>GS</sub> = 0)	10	00	V
$V_{DGR}$	Drain- gate Voltage (R <sub>GS</sub> = 20 kΩ)	10	00	V
$V_{GS}$	Gate-source Voltage	±	20	V
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 25 °C	16	11	А
I <sub>D</sub>	Drain Current (continuous) at T <sub>c</sub> = 100 °C	11	7.8	А
I <sub>DM</sub> (•)	Drain Current (pulsed)	64	64	А
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	90	40	W
	Derating Factor	0.6	0.27	W/°C
Viso	Insulation Withstand Voltage (DC)	-	2000	V
T <sub>stg</sub>	Storage Temperature	-65 to 175		°C
Tj	Max. Operating Junction Temperature	17	75	°C

<sup>(•)</sup> Pulse width limited by safe operating area

(1) I<sub>SD</sub>  $\leq$ 16 A, di/dt  $\leq$  200 A/ $\mu$ s, V<sub>DD</sub>  $\leq$  V<sub>(BR)DSS</sub>, Tj  $\leq$  T<sub>JMAX</sub>

March 1999 1/6

#### THERMAL DATA

			TO-220	TO-220FI	
R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	1	3.75	°C/W
1,	Thermal Resistance Junction-ambient Thermal Resistance Case-sink	Max Typ	62 0.	-	°C/W
	Maximum Lead Temperature For Soldering P	<i>,</i> ,	30	-	°C

#### **AVALANCHE CHARACTERISTICS**

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by $T_j$ max, $\delta < 1\%$ )	16	А
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting $T_j = 25$ °C, $I_D = I_{AR}$ , $V_{DD} = 50$ V)	100	mJ

# **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25$ $^{\circ}C$ unless otherwise specified) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A$ $V_{GS} = 0$	100			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating$ $T_c = 125  ^{\circ}C$			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	$V_{GS} = \pm 20 \text{ V}$			± 100	nA

## ON (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \mu A$	2	3	4	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	$V_{GS} = 10V$ $I_D = 8$ A		0.12	0.16	Ω
I <sub>D(on)</sub>	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10 \text{ V}$	16			A

#### **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (*)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_D = 8 A$	5	8		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}$ f = 1 MHz $V_{GS} = 0$		950 150 50	1300 270 70	pF pF pF

2/6

## **ELECTRICAL CHARACTERISTICS** (continued)

#### **SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Time Rise Time	$V_{DD} = 50 \text{ V}$ $I_{D} = 8 \text{ A}$ $R_{G} = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$		12 20	16 28	ns ns
$egin{array}{c} Q_g \ Q_{gs} \ Q_{gd} \end{array}$	Total Gate Charge Gate-Source Charge Gate-Drain Charge	V <sub>DD</sub> =80 V I <sub>D</sub> =16 A V <sub>GS</sub> = 10 V		32 9 13	44	nC nC nC

#### **SWITCHING OFF**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
tf	1	$V_{DD} = 80 \text{ V}$ $I_{D} = 16 \text{ A}$ $R_{G} = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$		11 12 25	15 17 35	ns ns ns

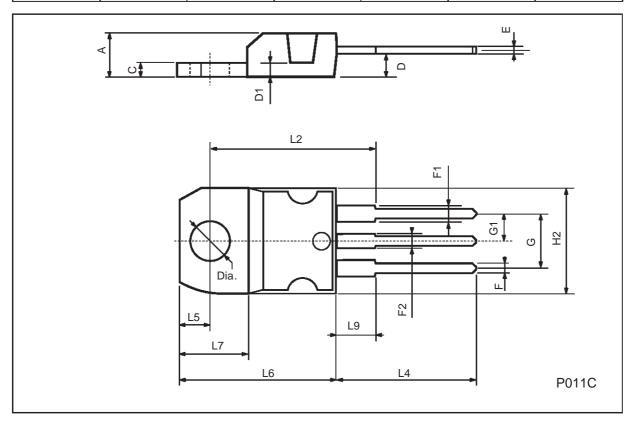
#### SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (•)	Source-drain Current Source-drain Current (pulsed)				16 64	A A
V <sub>SD</sub> (*)	Forward On Voltage	$I_{SD} = 16 \text{ A}  V_{GS} = 0$			1.6	V
t <sub>rr</sub>	Reverse Recovery Time	$I_{SD} = 16 \text{ A}$		150		ns
Q <sub>rr</sub>	Reverse Recovery Charge	,		0.8		μС
I <sub>RRM</sub>	Reverse Recovery Current			10		A

<sup>(\*)</sup> Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %
(•) Pulse width limited by safe operating area

# **TO-220 MECHANICAL DATA**

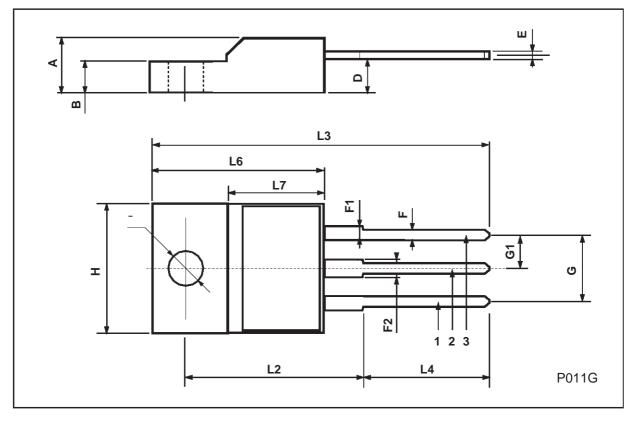
DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α	4.40		4.60	0.173		0.181
С	1.23		1.32	0.048		0.051
D	2.40		2.72	0.094		0.107
D1		1.27			0.050	
Е	0.49		0.70	0.019		0.027
F	0.61		0.88	0.024		0.034
F1	1.14		1.70	0.044		0.067
F2	1.14		1.70	0.044		0.067
G	4.95		5.15	0.194		0.203
G1	2.4		2.7	0.094		0.106
H2	10.0		10.40	0.393		0.409
L2		16.4			0.645	
L4	13.0		14.0	0.511		0.551
L5	2.65		2.95	0.104		0.116
L6	15.25		15.75	0.600		0.620
L7	6.2		6.6	0.244		0.260
L9	3.5		3.93	0.137		0.154
DIA.	3.75		3.85	0.147		0.151



**57** 

# **ISOWATT220 MECHANICAL DATA**

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
Е	0.4		0.7	0.015		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



**57** 

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47/